

What is claimed is:

1. An electron tube having a ring-less getter of a tablet shape in a vessel,

5 wherein a light is irradiated on the ring-less getter to thereby activate the ring-less getter.

2. The electron tube of claim 1, wherein the ring-less
getter is an evaporation type ring-less getter; and an
10 evaporated getter generated by irradiating the light on the
ring-less getter forms a getter film in the vessel of the
electron tube.

3. The electron tube of claim 1, wherein the ring-less
15 getter is a non-evaporation type ring-less getter; and the
light is irradiated on the ring-less getter to selectively
heat the ring-less getter, thereby activating the ring-less
getter.

20 4. The electron tube of claim 1, wherein the ring-less
getter is installed on the vessel including at least one
substrate of the electron tube.

5. The electron tube of claim 1, wherein the ring-less
25 getter is installed on a component of the electron tube.

6. The electron tube of claim 1, wherein the ring-less getter is mounted on a metallic layer formed in the vessel and a metallic wire is hanged to the ring-less getter and then two end portions of the metallic wire are welded to the metallic layer.

7. The electron tube of claim 1, wherein two end portions of a metallic wire installed on the ring-less getter are welded to a metallic layer side formed in the vessel.

8. The electron tube of claim 7, wherein the metallic wire is mounted on the metallic layer on the ring-less getter.

9. The electron tube of claim 8, wherein the metallic wire is mounted on the metallic layer parallel to a display region of the electron tube.

10. The electron tube of claim 6 or 7, wherein the vessel is a vacuum vessel; the welding is performed by employing an ultrasonic bonding; the metallic wire is a bonding wire; and the metallic layer is a metallic thin film.

11. The electron tube of claim 1, wherein the ring-less getter includes a getter material layer and a metallic layer; and the metallic layer of the ring-less getter is welded to a corresponding metallic layer formed in the

vessel.

12. The electron tube of claim 1, wherein the ring-less
getter includes a getter material layer and a metallic layer
5 formed by press forming getter material powder and metal
powder, respectively; and the metallic layer of the ring-
less getter is welded to a metallic layer formed in the
vessel.

13. The electron tube of claim 1, wherein the ring-less
getter includes a getter material layer and a metallic layer
10 formed by press forming the getter material powder and a
metal film/plate, respectively; and the metallic layer of
the ring-less getter is welded to a metallic layer formed in
15 the vessel.

14. The electron tube of claim 1, wherein the ring-less
getter includes a getter material layer and a metallic wire
20 formed by pressing getter material powder and a metal wire,
respectively; and the metallic wire of the ring-less getter
is welded to a metallic layer formed in the vessel.

15. The electron tube of claim 1, wherein the ring-less
getter includes a metallic layer and a getter material layer
25 having a getter material film; and the metallic wire of the
ring-less getter is welded to a metallic layer formed in the

vessel.

16. The electron tube of one of claims 11 to 15, wherein the getter material layer of the ring-less getter is evaporated by the light and there is formed a getter mirror film on an inner side of a corresponding substrate or a corresponding component of the electron tube facing to the substrate or the component where the ring-less getter is fixed.

17. The electron tube of one of claims 11 to 15, wherein the light is irradiated on the getter material layer of the ring-less getter from outside of a corresponding substrate facing to the substrate or the component where the ring-less getter is fixed; and there is formed a getter mirror film on an inner side of the corresponding substrate.

18. The electron tube of one of claims 11 to 15, wherein the vessel is a vacuum vessel; the welding is performed by employing an ultrasonic bonding; and the metallic wire is a bonding wire; and the metallic layer is a metallic thin film.

19. The electron tube of one of claims 1, 6, 7 and 11 to 15, wherein the electron tube is a fluorescent display device.

20. A method for manufacturing an electron tube including a front substrate and a back substrate,

wherein a wiring and an electrode are formed on the front substrate and/or the back substrate; a component is mounted on the front substrate and/or the back substrate; a ring-less getter is mounted on at least one of the front substrate, the back substrate and the component; a vessel is assembled and sealed so that the front substrate faces the back substrate; a light is irradiated on the ring-less getter from outside of the sealed vessel, thereby activating the ring-less getter.

21. A method for manufacturing an electron tube including a front substrate and a back substrate,

wherein a wiring and an electrode are formed on the front substrate and/or the back substrate; a component having a ring-less getter of a tablet shape installed thereon is mounted on the front substrate and/or the back substrate; a vessel is assembled and sealed so that the front substrate faces the back substrate; a light is irradiated on the ring-less getter from outside of the sealed vessel, thereby activating the ring-less getter.

22. The method of claim 20 or 21, wherein the ring-less getter is an evaporation type ring-less getter; and evaporated getter generated by irradiating the light on the

ring-less getter forms a getter film in the vessel of the electron tube.

23. The method of claim 20 or 21, wherein the light is a
5 laser beam.

24. The method of claim 20 or 21, wherein the ring-less
getter is installed by employing either an ultrasonic
bonding technique or an ultrasonic bonding technique.
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